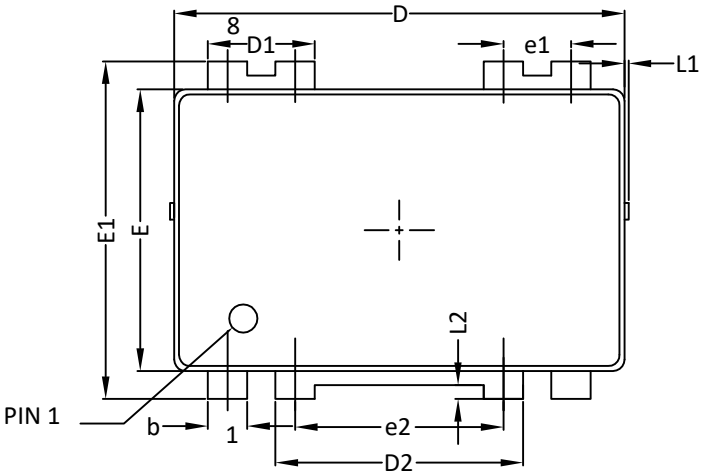
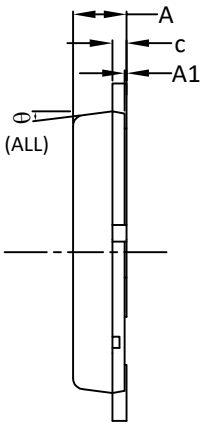
ALPHA & OMEGA SEMICONDUCTOR

Document No.	PO-00254
Version	C

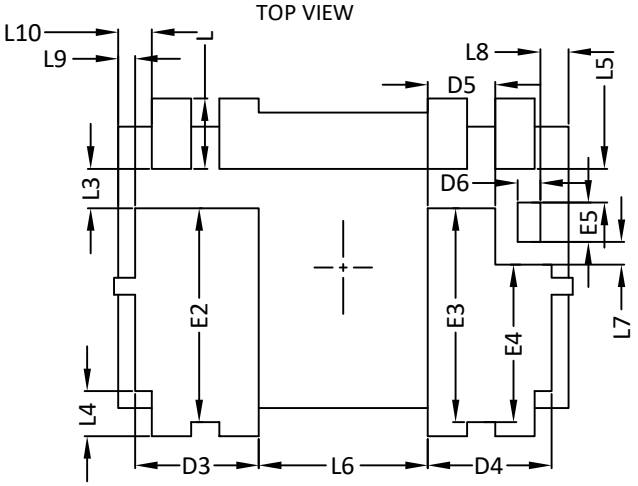
DFN8x6_8L_EP2_P PACKAGE OUTLINE



TOP VIEW

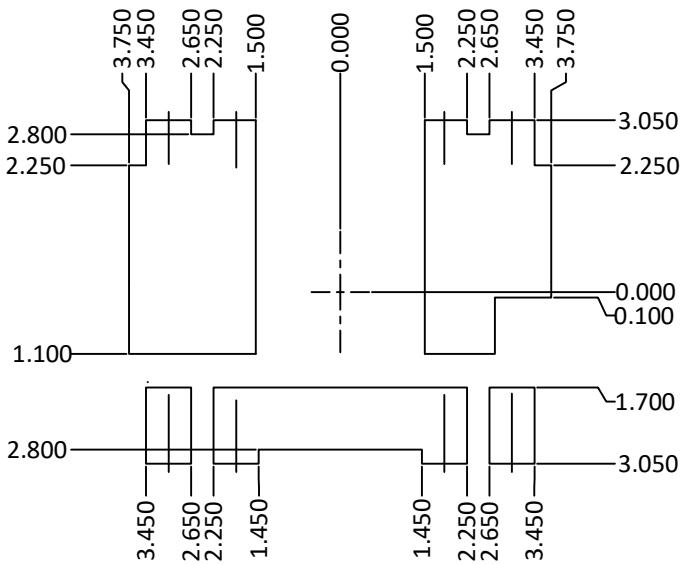


SIDE VIEW



BOTTOM VIEW

RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.85	0.95	1.05
A1	0.00	-	0.05
b	0.60	0.70	0.80
c	0.20	0.25	0.30
D	7.80	8.00	8.20
D1	1.80	1.90	2.00
D2	4.30	4.40	4.50
D3	2.10	2.20	2.30
D4	2.10	2.20	2.30
D5	1.10	1.20	1.30
D6	0.30	0.40	0.50
E	4.80	5.00	5.20
E1	5.80	6.00	6.20
E2	3.70	3.80	3.90
E3	3.70	3.80	3.90
E4	2.70	2.80	2.90
E5	0.60	0.70	0.80
e1	1.2BSC		
e2	3.7BSC		
L	1.15	1.25	1.35
L1	0.00	-	0.15
L2	0.25REF		
L3	0.7REF		
L4	0.70	0.80	0.90
L5	0.50	0.60	0.70
L6	2.90	3.00	3.10
L7	0.30	0.40	0.50
L8	0.40	0.50	0.60
L9	0.20	0.30	0.40
L10	0.50	0.60	0.70
θ	0°	-	12°

NOTE
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
   MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
2.THIS PACKAGE WAS QUALIFIED USING IR REFLOW PROCESS (JEDEC STANDARD). FOR USAGE IN OTHER SOLDERING PROCESSES, PLEASE CONTACT LOCAL AOS REPRESENTATIVES.

UNIT: mm